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DIODES, VOLTAGE REFERENCE, 6.2 VOLTS, IN DO35 CASE, BASED ON TYPES 1N821A TO 1N829A ESCC Detail Specification No. 5102/008

ISSUE 1 October 2002





ESCC Detail Specification

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DIODES, VOLTAGE REFERENCE, 6.2 VOLTS, IN DO35 CASE,

BASED ON TYPES 1N821A TO 1N829A

ESA/SCC Detail Specification No. 5102/008



space components coordination group

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Issue/Rev.	Date	SCCG Chairman	ESA Director General or his Deputy	
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DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	CHANGE Reference Item	Approved DCR No.
		This issue supersedes Issue 3 and incorporates all modifications agreed on the basis of Policy DCR 21025 and the following DCR's:- Cover page DCN Contents : Paras. 4.2.3, 4.2.4 and 4.2.5 moved to page 10 Para. 4.2.3 : Deletion of X-Rays Table 2 : Reformated Table 3 : Reformated Table 4 : Reformated Table 6 : Reformated Table 6 : Z _Z limited changed Appendix 'A' : Test document changed : Units for test pressure changed	None None None 22236 23141 23141 23141 23141 22238 24029 24028
'A'	July '93	P1. Cover Page P2. DCN P4. ToC : Table 1 renumbered to 1(b) : Table 1(a) added P9. Para. 4.2.2 : PIND deviation amended P10. Para. 4.2.3 : Radiographic Inspection deviation amended This document has been transferred from hardcopy to electronic format. The content is unchanged but minor differences in presentation exist.	None None 21021 21021 21043 21049



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1. GENERAL

1.1 <u>SCOPE</u>

This specification details the ratings, physical and electrical characteristics, test and inspection data for Diodes, Voltage Reference, 6.2 Volts, in DO35 case, based on Types 1N821A to 1N829A.

It shall be read in conjunction with ESA/SCC Generic Specification No. 5000, the requirements of which are supplemented herein.

1.2 COMPONENT TYPE VARIANTS

Variants of the basic diodes specified herein, which are also covered by this specification, are listed in Table 1(a).

1.3 MAXIMUM RATINGS

The maximum ratings, which shall not be exceeded at any time during use or storage, applicable to the diodes specified herein, are scheduled in Table 1(b).

1.4 PARAMETER DERATING INFORMATION

The derating information applicable to the diodes specified herein is shown in Figure 1.

1.5 PHYSICAL DIMENSIONS

The physical dimensions of the diodes specified herein are shown in Figure 2.

1.6 FUNCTIONAL DIAGRAM

The functional diagram, showing lead identification, of the diodes specified herein, is shown in Figure 3.

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TABLE 1(a) - TYPE VARIANTS

(1)	(2)	(3)	(4)
Variant	Based on Type	TZ _{VZ} (%/°C)	Lead Material and Finish
01	1N821A	0.01	C2
02	1N823A	0.005	C2
03	1N825A	0.002	C2
04	1N827A	0.001	C2
05	1N829A	0.0005	C2
06	1N821A	0.01	C3 OR C4
07	1N823A	0.005	C3 OR C4
08	1N825A	0.002	C3 OR C4
09	1N827A	0.001	C3 OR C4
10	1N829A	0.0005	C3 OR C4

TABLE 1(b) - MAXIMUM RATINGS

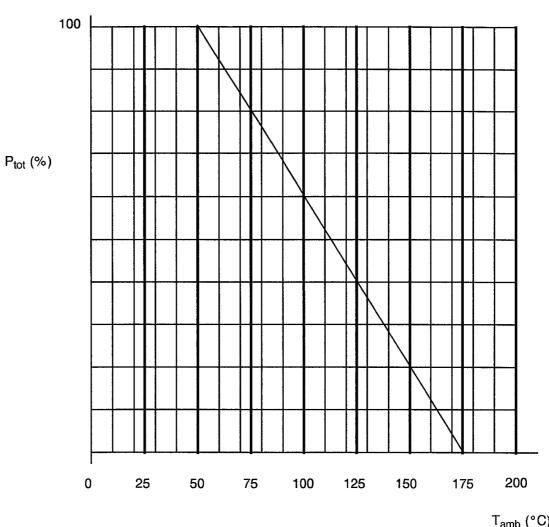
No.	CHARACTERISTIC	SYMBOL	MAXIMUM RATING	UNIT	REMARKS
1	Power Dissipation	P _{tot}	400	mW	T _{amb} ≤ +50°C
2	Operating Temperature Range	T _{op}	-55 to +175	°C	T _{amb}
3	Storage Temperature Range	T _{stg}	- 65 to + 175	°C	
4	Soldering Temperature	T _{sol}	+ 260	°C	Time: ≤10 seconds; Distance from case: ≥ 1.5mm



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FIGURE 1 - PARAMETER DERATING INFORMATION



Power Dissipation Versus Temperature

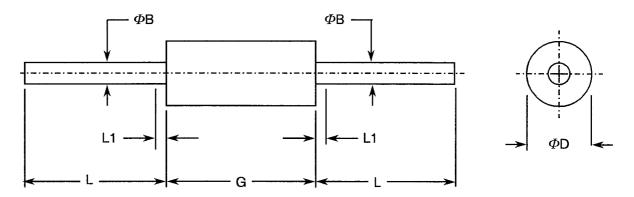
T_{amb} (°C)



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FIGURE 2 - PHYSICAL DIMENSIONS



Millimetre dimensions are derived from original inch dimensions.

CVMPOL	INC	INCHES		ETRES	NOTEO	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
ΦВ	.018	.022	.458	.558	-	
ΦD	.060	.090	1.53	2.28	1	
G	.120	.200	3.05	5.08	1	
L	.500	-	12.70	-	-	
L1	-	.050	-	1.27	2	

NOTES

- 1. Package contour optional within cylinder of diameter ΦD and length G. Slugs, if any, shall be included within this cylinder but shall not be subject to the minimum limit of ΦD .
- 2. Lead diameter not controlled in this zone to allow for flash, lead finish build-up, and minor irregularities other than slugs.

FIGURE 3 - FUNCTIONAL DIAGRAM



- 1. Anode
- 2. Cathode

NOTES

1. The cathode end shall be marked with a coloured ring.



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2. APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:-

- (a) ESA/SCC Generic Specification No. 5000 for Discrete Semiconductors.
- (b) MIL-STD-750, Test Methods and Procedures for Semiconductor Devices.
- (c) MIL-STD-202, Test Methods for Electronic and Electrical Component Parts.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply.

4. **REQUIREMENTS**

4.1 GENERAL

The complete requirements for procurement of the diodes specified herein are stated in this specification and ESA/SCC Generic Specification No. 5000 for Discrete Semiconductors. Deviations from the Generic Specification applicable to this specification only, are listed in Para. 4.2.

Deviations from the applicable Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESA/SCC requirements and do not affect the components' reliability, are listed in the appendices attached to this specification.

4.2 DEVIATIONS FROM GENERIC SPECIFICATION

4.2.1 Deviations from Special In-process Controls

None.

4.2.2 Deviations from Final Production Tests (Chart II)

- (a) Bond Strength Test: Shall not be performed.
- (b) Die Shear Test: Shall not be performed.
- (c) Para. 9.7, Particle Impact Noise Detection (PIND) Test: Not applicable.
- (d) Thermal Shock Test: Shall be performed in accordance with Test Method 107, Condition 'B', of MIL-STD-202.



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4.2.3 <u>Deviations from Burn-in and Electrical Measurements (Chart III)</u>

- (a) H.T.R.B. Test: Shall not be performed.
- (b) Para. 9.12, Radiographic Inspection: Not applicable.

4.2.4 Deviations from QualificationTests (Chart IV)

- (a) Bond Strength Test: Shall not be performed.
- (b) Die-shear Test: Shall not be performed.

4.2.5 <u>Deviations from Lot Acceptance Tests (Chart V)</u>

None.

4.3 MECHANICAL REQUIREMENTS

4.3.1 Dimension Check

The dimensions of the diodes specified herein shall be checked. They shall conform to those shown in Figure 2.

4.3.2 Weight

The maximum weight of the diodes specified herein shall be 0.2 grammes.

4.3.4 Terminal Strength

The requirements for terminal strength testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The test conditions shall be as follows:-

Test Condition:

'A' (Tension).

Applied Force :

5.0 Newtons.

Duration

10 seconds

4.4 MATERIALS AND FINISHES

The materials and finishes shall be as specified herein. Where a definite material is not specified, a material which will enable the diodes specified herein to meet the performance requirements of this specification shall be used. Acceptance or approval of any constituent material does not guarantee acceptance of the finished product.

4.4.1 <u>Case</u>

Glass, hermetically sealed.

4.4.2 <u>Lead Material and Finish</u>

The lead material shall be Type 'C' with either Type '2' or Type '3 or 4' finish in accordance with the requirements of ESA/SCC Basic Specification No. 23500. (See Table 1(a) for Type Variants).



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4.5 MARKING

4.5.1 General

The marking of all components delivered to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 21700. Each component shall be marked in respect of:-

- (a) Lead Identification.
- (b) The SCC Component Number.
- (c) Traceability Information.

4.5.2 Lead Identification

Lead identification shall be as shown in Figures 2 and 3 of this specification.

4.5.3 The SCC Component Number

Each component shall bear the SCC Component Number which shall be constituted and marked as follows:

Detail Specification Number	510200802B
Type Variant (see Table 1(a))	
Testing Level (B or C, as applicable)	

4.5.4 Traceability Information

Each component shall be marked in respect of traceability information in accordance with the requirements of ESA/SCC Basic Specification No. 21700.

4.5.5 Marking of Small Components

When it is considered that the component is too small to accommodate the marking as specified above, as much as space permits shall be marked. The order of precedence shall be as follows:-

- (a) Lead Identification.
- (b) The SCC Component Number.
- (c) Traceability Information.

The marking information in full shall accompany each component in its primary package.



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4.6 ELECTRICAL MEASUREMENTS

4.6.1 Electrical Measurements at Room Temperature

The parameters to be measured at room temperature are scheduled in Table 2. The measurements shall be performed at T_{amb} = +22 ±3 °C.

4.6.2 Electrical Measurements at High and Low Temperatures

The parameters to be measured at high and low temperatures are scheduled in Table 3.

4.6.3 Circuits for Electrical Measurements

Circuits for use in performing the electrical measurements listed in Tables 2 and 3 of this specification are shown in Figure 4.

4.7 BURN-IN TESTS

4.7.1 Parameter Drift Values

The parameter drift values applicable to burn-in are specified in Table 4 of this specification. Unless otherwise stated, the measurements shall be performed at T_{amb} = +22 ±3 °C. The parameter drift values (Δ) applicable to the parameters scheduled, shall not be exceeded. In addition to these drift value requirements, the appropriate limit value specified for a given parameter in Table 2 shall not be exceeded.

4.7.2 Conditions for Burn-in

The requirements for burn-in are specified in Section 7 of ESA/SCC Generic Specification No. 5000. The conditions for burn-in shall be as specified in Table 5 of this specification.

4.7.3 Electrical Circuits for Burn-in

Circuits for use in performing the burn-in tests are shown in Figure 5 of this specification.



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TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS

No.	No. CHARACTERISTICS S	SYMBOL	MIL-STD-750	TEST CONDITION	LIMITS		UNIT
NO. CHARACTERISTICS	STIVIDOL	TEST METHOD	TEST CONDITION	MIN.	MAX.		
1	Zener Voltage	Vz	4022	I _Z = 7.5mA	5.9	6.5	V
2	Reverse Current	l _R	4016	V _R = 4.5 V	· •	150	μΑ

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURES - a.c. PARAMETERS

No.	No CHADACTEDISTICS	ARACTERISTICS SYMBOL MIL-STD-750		TEST CONDITION	LIMITS		UNIT
140.	OHARAOTERISTIOS	OTWIDOL	TEST METHOD	TEST CONDITION	MIN.	MAX.	ONIT
3	Small Signal Breakdown Impedance	Z _Z	4051	I _Z = 7.5mA	-	10	Ω

FIGURE 4 - TEST CIRCUITS

Not applicable.



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TABLE 3 - ELECTRICAL MEASUREMENTS AT HIGH AND LOW TEMPERATURES

No.	No. CHARACTERISTICS SYMB	SVMROI	MIL-STD-750	TEST CONDITION	LIM	ITS	UNIT
140.	ONAINOTENIOTIO	OTWIDOL	TEST METHOD		MIN.	MAX.	ONIT
4	Temperature Coeff. of Zener Voltage	TC _{VZ}	4071	-55/+25/ +100 °C I _Z =7.5mA	-	(1)	%/°C

NOTES

1. See Column 3 of Table 1(a).

TABLE 4 - PARAMETER DRIFT VALUES

No.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITION	CHANGE LIMITS (Δ)	UNIT
1	Zener Voltage	V _Z	As per Table 2	As per Table 2	± 10	mV
3	Small Signal Breakdown Impedance	Z _Z	As per Table 2	As per Table 2	±10	%

TABLE 5 - CONDITIONS FOR BURN-IN

No.	CHARACTERISTIC	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T _{amb}	+ 150	°C
2	Zener Current	IZ	7.5	mA

FIGURE 5 - ELECTRICAL CIRCUIT FOR BURN-IN

Not applicable.



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4.8 <u>ENVIRONMENTAL AND ENDURANCE TESTS (CHARTS IV AND V OF ESA/SCC GENERIC SPECIFICATION NO. 5000)</u>

4.8.1 Electrical Measurements on Completion of Environmental Tests

The parameters to be measured on completion of environmental tests are scheduled in Table 2. The measurements shall be performed at $T_{amb} = +22 \pm 3$ °C.

4.8.2 Electrical Measurements at Intermediate Points and on Completion of Endurance Tests

The parameters to be measured at intermediate points and on completion of endurance testing are scheduled in Table 6.

4.8.3 Conditions for Operating Life Tests (Part of Endurance Testing)

The requirements for operating life testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The conditions for operating life testing shall be the same as specified in Table 5 for the burn-in test.

4.8.4 Electrical Circuits for Operating Life Tests

The circuit to be used for performance of the operating life test shall be the same as shown in Figure 5 for burn-in.

4.8.5 Conditions for High Temperature Storage Test (Part of Endurance Testing)

The requirements for the high temperature storage test are specified in ESA/SCC Generic Specification No. 5000. The temperature to be applied shall be the maximum storage temperature specified in Table 1(b) of this specification.



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TABLE 6 - ELECTRICAL MEASUREMENTS AT INTERMEDIATE POINTS AND ON COMPLETION OF ENDURANCE TESTING

No.	CHARACTERISTICS	SVMBOL	SPEC. AND/OR	TEST	LIMITS		UNIT
NO.	CHAINCILIISTICS	STWIDGE	TEST METHOD	CONDITION	MIN.	MAX.	OIVII
1	Zener Voltage	l _R	As per Table 2	As per Table 2	5.9	6.5	V
3	Small Signal Breakdown Impedance	Z _Z	As per Table 2	As per Table 2	-	10	Ω



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APPENDIX 'A'

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AGREED DEVIATIONS FOR THOMSON-CSF

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS	APPROVED DCR
Para's 4.2.4 and 4.2.5	Deviations from Environmental and Endurance Tests (Chart IV) and from Lot Acceptance Tests (Chart V)	
	"Moisture Resistance", Para 9.16, according to MIL-STD-750, Method 1021, shall be replaced by "Climatic Sequence" according to IEC 68-1 with the following conditions:	24029
	- Phase 'D': Option 2, 5 cycles;	
	- Phase 'F' (Low Air Pressure): Not applicable.	
	2. "Seal Test", Para's 9.8.1 and 9.8.2 according to MIL-STD-750, Method 1071, Conditions 'C' and 'H', shall be replaced by "Seal Test" according to IEC 68-2-17, Test QI (Bomb Pressure Test) with the following conditions:	24028
	- The pressure within the vessel shall be 210N/cm ² .	
	- The duration of conditioning shall be 4 hours.	
	 Final measurements: I_R with the limits as specified in Table 2 of this Detail Specification. 	